PATENT ABSTRACTS OF JAPAN

(11) Publication number: 03035018 A

(43) Date of publication of application: 15.02.91

(21) Application number: 01168892 (71) Applicant: TONEN CORP
(22) Date of filing: 30.06.89 (72) Inventor: WADA SADAHISA MURAKAMI SHINKICHI WATABE OSAMU INOUE HIROSHI

(54) EPOXY RESIN COMPOSITION

(57) Abstract:

PURPOSE: To obtain the title composition useful as a matrix resin for high-performance composite material, suitable for prepreg having excellent storage stability, comprising a tetrafunctional epoxy resin as a main component and a specific diaminodiphenylsulfone as a curing agent.

CONSTITUTION: Diaminodiphenylsulfone(DDS)

containing si50wt.% particles having si13µm particle diameter as a curing agent is dispersed in a granular state into a tetrafunctional epoxy resin as a main component and optionally the blend is mixed with a curing promoter such as imidazole compound, <50wt.% another epoxy resin (bisphenol A type epoxy resin), a thermoplastic resin, a filler, etc., to give the aimed composition. The amount of active hydrogen of amine of DDS blended is 0.4-1.5 equivalent based on epoxy group.

COPYRIGHT: (C)1991, JPO& Japio